

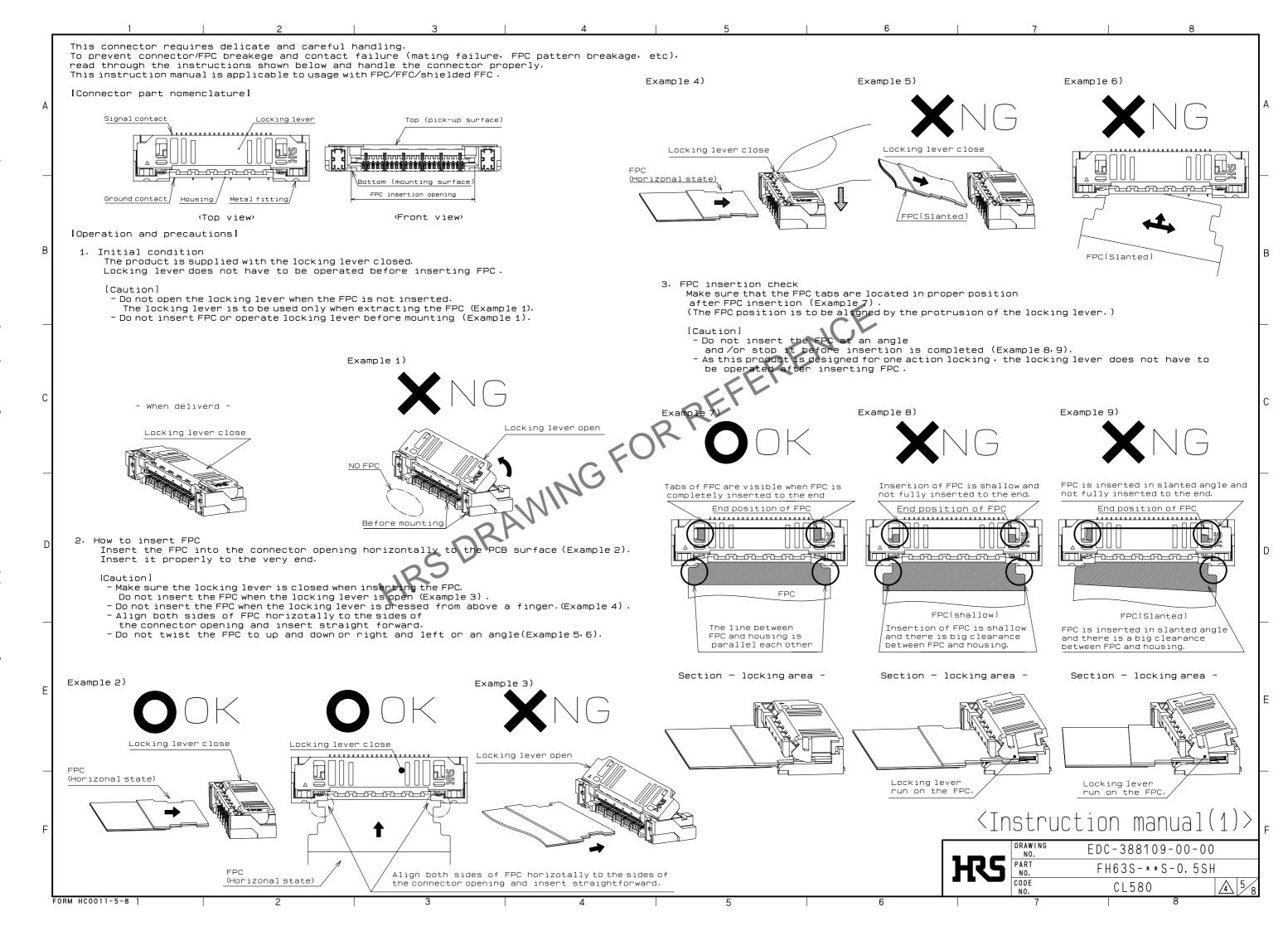
Part No.	Code Number	Number of	Din	Dimension of connector , PCB mounting pattern , metal mask , FPC , FFC , and shielded FFC									Dimension of drawing for packing							
		contacts	Α	В	С	D	Е	F	G	Н	J	K	L	М	Р	Q	R	S	U	V
FH63S-10S-0.5SH	CL580-4414-0-00	10	12.7	4.5	5.55	4	2	7.15	9.9	3	7.1	5.5	9.1	4.9	24	-	11.5	14.1	29.4	25.4
FH63S-20S-0.5SH	CL580-4419-0-00	20	17.7	9.5	6.55	9	1.5	12.15	14.9	6	12.1	10.5	14.1	9.9	32	28.4	14.2	19.1	37.4	33.4
FH63S-30S-0.5SH	CL580-4415-0-00	30	22.7	14.5	5.55	14	2	17.15	19.9	8	17.	15.5	19.1	14.9	44	40.4	20.2	24.1	49.4	45.4
FH63S-40S-0.5SH	CL580-4416-0-00	40	27.7	19.5	10.55	19	1.5	22.15	24.9	11	22.1	20.5	24.1	19.9	44	40.4	20.2	29.1	49.4	45.4
FH63S-50S-0.5SH		50	32.7	24.5	15.55	24	2	27.15	29.9	13	27.1	25.5	29.1	24.9	56	52.4	26.2	34.1	61.4	57.4
FH63S-60S-0.5SH		60	37.7	29.5	20.55	29	1.5	32.15	34.9	16	32.1	30.5	34.1	29.9	56	52.4	26.2	39.1	61.4	57.4

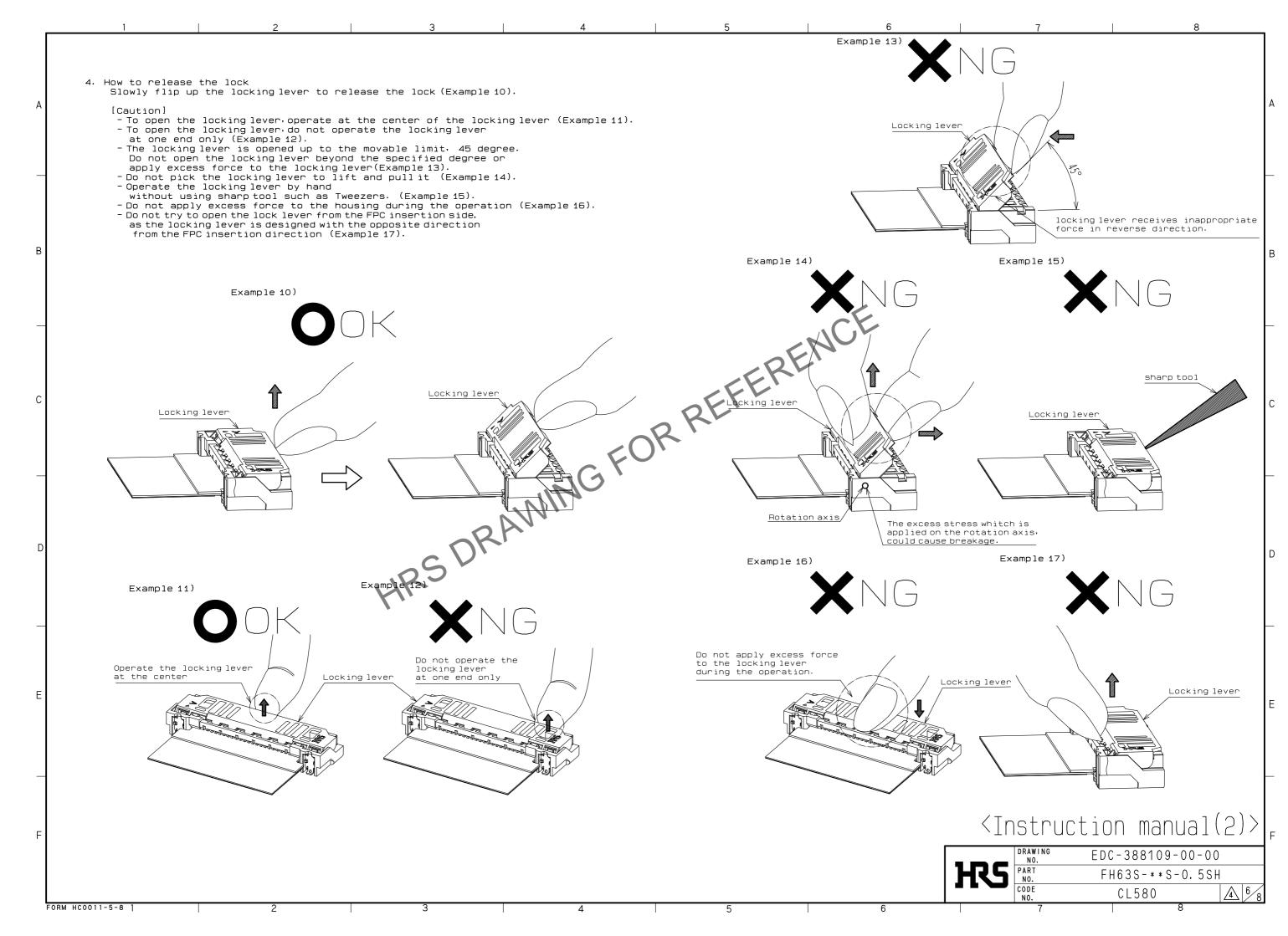
*The products without code number are currently under planning.

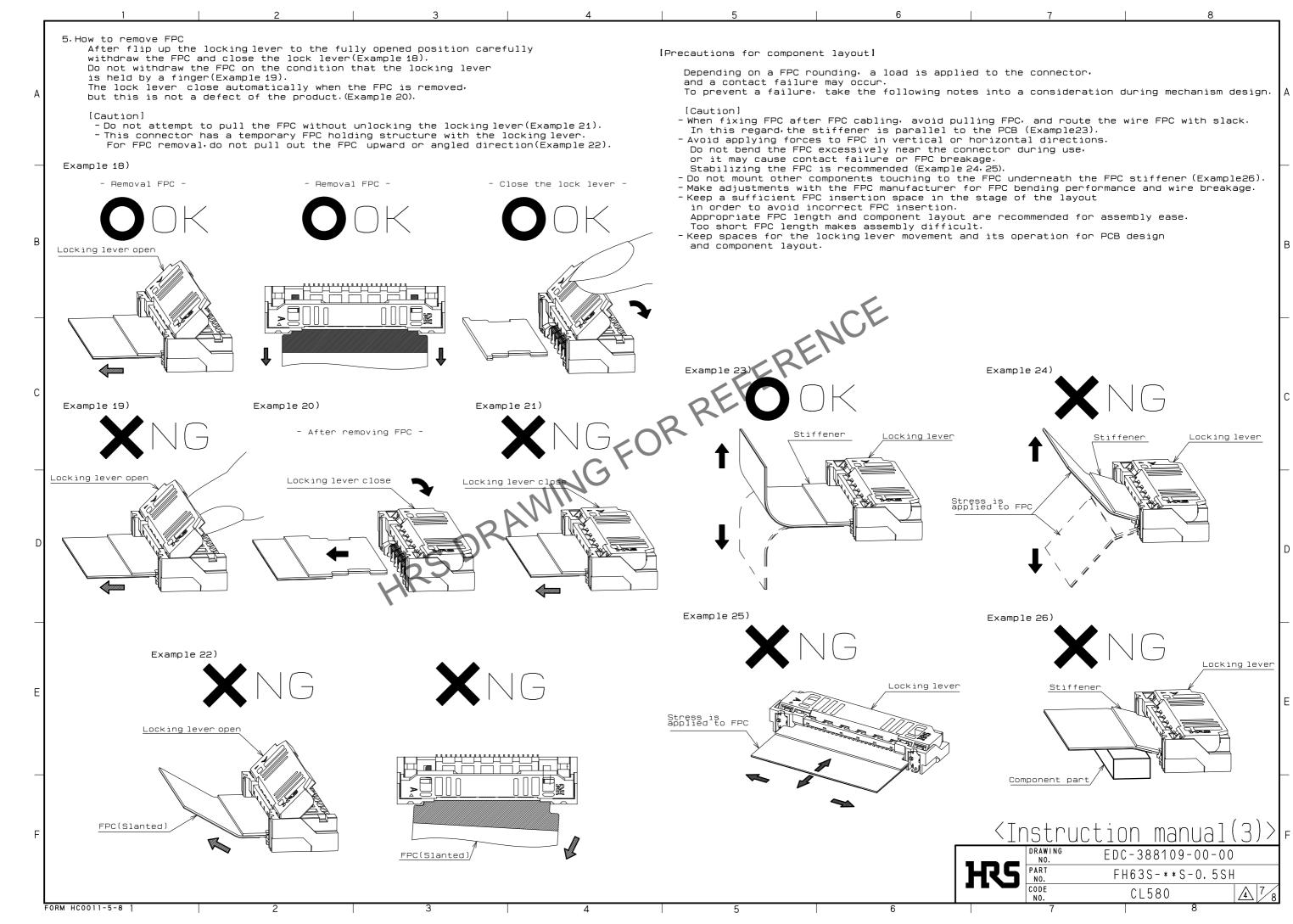
Please contact HIROSE for detailed information about product variation.

<Dimension table>

		DRAWING NO.	EDO	C-388109-00-0	0
	H 25	PART NO.	Fŀ	H63S-**S-0.5S	S H
		CODE NO.		CL580	4
		7		8	







| Instructions for mounting on the PCB|

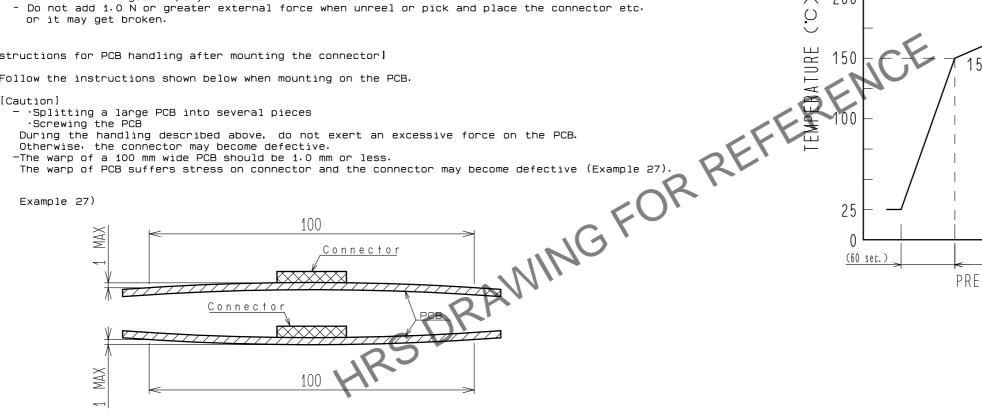
Follow the instructions shown below when mounting on the PCB.

[Caution]

- Refer to recommended layouts on the page 1 for PCB and stencil pattern Shorter pattern width than the recommended PCB dimension.
- could cause solder wicking and/or flux penetration.
- Larger pattern than the recommended stencil dimension, could cause solder wicking and/or flux penetration.
- Clearance underneath the contact lead and the housing is very small.
- In case solder resist and/or silk screening are applied on PCB underneath the connector. verify the thickness, or it could push up the connector bottom
- and may cause soldering defect and/or insufficient fillet formation.
- Apply reflow temperature profile within the specified conditions. In individual applications, the actual temperature may vary,
- depending on solder paste type volume/thickness and PCB size/thickness.
- Consult your solder paste and equipment manufacturer for specific recommendations. - Prevent warpage of PCB, where possible, since it can cause soldering failure
- even with 0.1 mm max coplanarity.
- When mounting on the flexible board, please make sure to put a stiffener on the backside of the flexible board.
- We recommend a glass epoxy material with the thickness of 0.3 mm min.
- Do not add 1.0 N or greater external force when unreel or pick and place the connector etc. or it may get broken.

| Instructions for PCB handling after mounting the connector

Follow the instructions shown below when mounting on the PCB.



|Instructions on manual soldering|

Follow the instructions shown below when soldering the connector manually during repair work, etc.

[Caution]

- Do not perform manual soldering with the FPC inserted into the connector.
- Do not heat the connector excessively. Be very careful not to let the soldering iron contact
- any parts other than connector leads. Otherwise, the connector may be deformed or melt.
- Do not supply excessive solder (or flux).
- If excessive solder (or flux) is supplied on the terminals, solder or flux may adhere

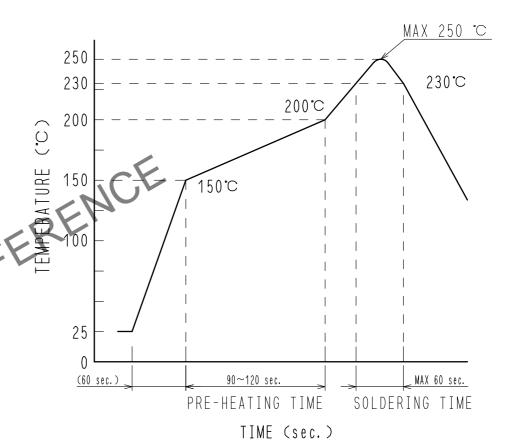
to the contacts, resulting in poor contact.

Supplying excessive solder to the metal fittings may hinder locking lever rotation. resulting in breakage of the connector.

[Recommended reflow temperature profile]

The temperatures mentioned above refer to the PCB surface temperature near the connector leads. In individual applications the actual temperature may vary, depending on solder paste type, volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.

- -Reflow method:IR reflow
- Number of reflow cycles:2 cycles MAX.



<Instruction manual(4)>

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DRAWING EDC-388109-00-00 FH63S-**S-0.5SH CODE |A|8/8CL580

FORM HC0011-5-8 1